PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		

CONVEYING PARTY DATA

Name	Execution Date
Andy Tsen	05/10/2011
Jin-Ning Sung	05/10/2011
Po-Feng Tsai	05/10/2011
Jong-I Mou	05/10/2011
Yen-Wei Cheng	05/10/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Road 6
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13106711

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 214-651-5000

Email: ipdocketing@haynesboone.com
Correspondent Name: HAYNES AND BOONE, LLP
Address Line 1: 2323 Victory Avenue

Address Line 2: Suite 700

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.1801 - BRANDI S.

NAME OF SUBMITTER: Brandi W. Sarfatis

Total Attachments: 3

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OP \$40.00 13106711

2008-0868-CIP/24061.1801

Docket No.: 2008-0534 / 24061.1153 Customer No.: 42717

ASSIGNMENT

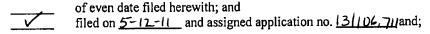
WHEREAS, we.	W	JΗ	ER	E/	AS.	we.
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(1)	Andy Tsen .	of	38, Floor 11, Alley 167, Chung-Cheng Road Chung-Ho City, Taipei County 235, Taiwan, R.O.C.
(2)	Jin-Ning Sung	of	No. 10, Alley 4, Lane 183, Kaifong Street Pingjhen City, Taoyuan County 324, Taiwan, R.O.C.
(3)	Po-Feng Tsai	of	5F, No. 92-1, Sec. 3, Neihu Road, Neihu District Hsinpu Township, Hsinchu County 30542, Taiwan, R.O.C.
(4)	Jong-I Mou	of	No. 11, Daxiang Road Hsinpu Township, Hsinchu County 30542, Taiwan, R.O.C.
(5)	Yen-Wei Cheng	of	3F, No. 14, Lane 43, Sec. 1, Chenggong Rd, Yonghe District New Taipei City 23452, Taiwan, R.O.C.

have invented certain improvements in

SYSTEM AND METHOD FOR IMPLEMENTING MULTI-RESOLUTION ADVANCED PROCESS CONTROL

for which we have executed an application for Letters Patent of the United States of America,



WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

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2008-0868-CIP/24061.1801

Docket No.: 2008-0534 / 24061.1153

Customer No.: 42717

invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Andy Tsen
Residence Address:	38, Floor 11, Alley 167, Chung-Cheng Road Chung-Ho City, Taipei County 235, Taiwan, R.O.C.
Dated: Maj 10.	2011 Any John Inventor Signature
Inventor Name:	Jin-Ning Sung
Residence Address:	No. 10, Alley 4, Lane 183, Kaifong Street Pingjhen City, Taoyuan County 324, Taiwan, R.O.C.
Dated: May 10.	Zoil Jin-Ming Sung Inventor Signature
Inventor Name:	Po-Feng Tsai
Residence Address:	5F, No. 92-1, Sec. 3, Neihu Road, Neihu District Hsinpu Township, Hsinchu County 30542, Taiwan, R.O.C.
Dated: Way (0	To Feng Tsai Inventor Signature

2008-0868-CIP/ 24061.1801

Docket No.: 2008-0534 / 24061:1153

Customer No.: 42717

Inventor Name:

e,

Jong-I Mou

Residence Address:

No. 11, Daxiang Road

Hsinpu Township, Hsinchu County 30542, Taiwan, R.O.C.

Dated: 5/20/2011

Inventor Signature

Inventor Name:

Yen-Wei Cheng

Residence Address:

3F, No. 14, Lane 43, Section 1, Chenggong Rd., Yonghe District

New Taipei City 23452, Taiwan, R.O.C.

Inventor Signature

Men - Wei Cheng